

### **REMARKS**

A Request for Continued Examination (RCE) is submitted herewith. Also submitted herewith is a Petition for a three-month extension of time. The final Office Action mailed August 14, 2002 and the references cited therein have been carefully considered. Claim 1 has been amended in a sincere effort to define more clearly and more specifically features of Applicant's invention which distinguish over the references of record.

The courtesy of Examiner Louie in granting a telephonic interview with the undersigned attorney is gratefully appreciated. The telephonic interview with Examiner Louie took place on Tuesday, January 14, 2003. During the interview, U.S. Patent No. 6,228,676 (Glenn, et al.) was discussed. Examiner Louie was courteous enough to suggest a structural feature in the chip-type semiconductor light-emitting device of the present invention which was not clearly presented in Claim 1 and which is not found in the Glenn, et al. patent. In particular, Examiner Louie suggested that Claim 1 be amended to define that the inner portion and the outer portion of the at least one of the pair of electrodes resides in the same plane, as this structure is not disclosed in the Glenn, et al. patent.

More specifically, and as shown in Figures 1A and 1B of the subject application, at least one of the electrodes 14 and 16 is formed with an inner portion (on the substrate center side) and an outer portion (on the terminal side), and the inner portion has a height which is less than the height of the outer portion to define a step 18 therebetween. The inner and the outer portions of the electrode (either or both of electrodes 14 and 16) reside in the same plane with one another. This can be seen from Figures 1A and 1B of the subject application, and the description of the outer and inner portions of the electrodes is found at page 4, lines 1-13 of the specification of the subject application.

This limitation, that the inner portion of the at least one of the pair of electrodes resides in the same plane as the outer portion of the at least one of the pair of electrodes, was not found in Claim 1 prior to the amendments made herein.

In the last Office Action, on page 2 thereof, the Examiner equated the metallization layer 22 to Applicant's electrodes, including an inner portion (contact 23) and an outer

portion (contact 27). The Office Action specifically referred to Figure 1 of the Glenn, et al. patent. During the telephonic interview with the undersigned attorney, Examiner Louie, with the Applicant's appreciation and thanks, advised the undersigned attorney that contact 23 (which he equated to the inner portion of one of electrodes 14, 16 in Applicant's invention) and contact 27 (which he equated to the outer portion of the same electrode) do not reside in the same plane, whereas Applicant's inner and outer portions of the electrode do. Examiner Louie suggested amending Claim 1 to add this structural limitation, which was not found in the claim prior to the amendment made herein, which will eliminate the Glenn, et al. patent as prior art.

Examiner Louie's helpful suggestions with respect to Claim 1 are acknowledged and gratefully appreciated. It is true that contacts 23 and 27 disclosed in the Glenn, et al. patent do not reside in the same plane, as clearly shown in Figure 1 of the Glenn, et al. patent, whereas the inner and outer portions of the electrode of Applicant's invention do, indeed, reside in the same plane, as clearly shown in Figures 1A and 1B.

In accordance with the Examiner's suggestions, Claim 1 has been amended herein to more specifically define that the inner portion of the at least one of the pair of electrodes resides in the same plane as the outer portion of the at least one of the pair of electrodes. This structure clearly distinguishes the claimed invention from that disclosed in the Glenn, et al. patent.

U.S. Patent No. 3,935,501 (Sterbal) was cited in combination with the Glenn, et al. patent to teach the encapsulation of an LED chip. However, it is clear from the Sterbal patent that the LED disclosed therein does not have the structure of the inner and outer portions of an electrode, forming a step therebetween, residing in the same plane as one another, as now more specifically defined by amended Claim 1. Accordingly, it is respectfully urged that Claim 1, as now more clearly and more specifically amended, patentably distinguishes over the Glenn, et al. and Sterbal patents and is allowable.

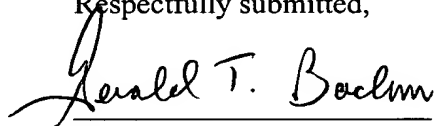
Claims 2-4 depend directly or indirectly from Claim 1, as now amended, and, therefore, incorporate the same new limitations as now found in amended Claim 1.

Accordingly, it is respectfully urged that Claims 2-4 patentably distinguish over the references of record for the same reasons submitted with respect to newly amended Claim 1.

If Examiner Louie has any further comments or suggestions with respect to Claim 1, or would like to see additional amendments to the claim, such suggestions and comments would be gratefully appreciated, and the undersigned attorney may be reached at the telephone number given below if and when Examiner Louie wishes to contact him.

In view of the foregoing amendments and remarks, entry and favorable consideration of amended Claim 1, reconsideration of Claims 2-4 and allowance of the application with Claims 1-4 are respectfully solicited.

Respectfully submitted,

A handwritten signature in cursive script, reading "Gerald T. Bodner", is written over a horizontal line.

Gerald T. Bodner  
Registration No. 30,449  
Attorney for Applicant

BODNER & O'ROURKE, LLP  
425 Broadhollow Road, Suite 108  
Melville, New York 11747  
Telephone: (631) 249-7500

**VERSION OF AMENDMENT WITH MARKS**  
**TO SHOW CHANGES MADE**

**IN THE CLAIMS:**

1. (Twice Amended) A chip-type semiconductor light-emitting device,  
comprising:

a pair of electrodes, at least one of said pair of electrodes including an inner portion  
and an outer portion, the inner portion of the at least one of said pair of electrodes residing in  
the same plane as the outer portion of the at least one of said pair of electrodes;

a semiconductor light-emitting chip electrically connected to said pair of electrodes;

a mold encapsulating said semiconductor light-emitting chip, said mold encapsulating  
said inner portion of at least one of said pair of electrodes, said outer portion of at least one of  
said pair of electrodes extending substantially laterally beyond said mold; and

a step formed in said inner portion of at least one of said pair of electrodes at an inside  
of said mold, said step having a height increasing from an outer side to an inner side of said  
mold.